



Atty. Dkt. No.: 200335-0037
U.S. Serial No.; 09/671,084

AMENDMENT RESPONSIVE TO OFFICE ACTION
(Paper No. 5) MAILED MARCH 22, 2001

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7/30/01

Responsive to an Office Action (Paper No. 5) mailed March 22, 2001, please amend the application, as follows:

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IN THE CLAIMS:

3. (Amended) The solder according to claim 1, wherein said solder has a copper dissolution rate of 0.20 $\mu\text{m}/\text{sec}$ or less.

4. (Amended) The solder according to claim 1, wherein said solder has a liquidus temperature of 240°C or lower.

5. (Amended) The solder according to claim 1, wherein said solder has a liquidus temperature of 230°C or lower.

11. (Amended) The solder according to claim 9, wherein said solder has a copper dissolution rate of 0.20 $\mu\text{m}/\text{sec}$ or less.

12. (Amended) The solder according to claim 9, wherein said solder has a liquidus temperature of 240°C or lower.

13. (Amended) The solder according to claim 9, wherein said solder has a liquidus temperature of 230°C or lower.